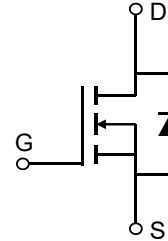


Description

Features

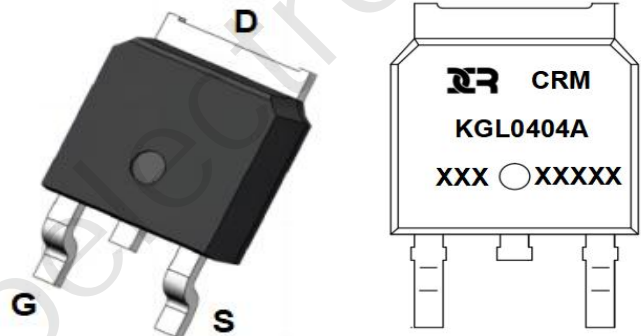
- 40V, 96A
- $R_{DS(ON)}$ Typ = 2.5mΩ @ $V_{GS} = 10V$
- $R_{DS(ON)}$ Typ = 4.2mΩ @ $V_{GS} = 4.5V$
- Advanced Split Gate Trench Technology
- Excellent $R_{DS(ON)}$ and Low Gate Charge
- 100% UIS TESTED!
- 100% ΔV_{ds} TESTED!



Schematic Diagram

Application

- Load Switch
- PWM Application
- Power Management



Marking and Pin Assignment

Package Marking and Ordering Information

Device	Marking	Package	Outline	Reel Size	Reel (pcs)	Per Carton (pcs)
CRMKGL0404A	CRMKGL0404A	TO-252-3L	TAPING	13"	2500	25000

Absolute Maximum Ratings (@ $T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Value	Units
V_{DS}	Drain-to-Source Voltage	40	V
V_{GS}	Gate-to-Source Voltage	±20	V
I_D	Continuous Drain Current	$T_C = 25^\circ\text{C}$	96
		$T_C = 100^\circ\text{C}$	57.6
I_{DM}	Pulsed Drain Current ⁽¹⁾	384	A
E_{AS}	Single Pulsed Avalanche Energy ⁽²⁾	121	mJ
P_D	Power Dissipation	$T_C = 25^\circ\text{C}$	52
$R_{\theta JC}$	Thermal Resistance, Junction to Case	2.4	°C/W
T_J, T_{STG}	Junction & Storage Temperature Range	-55 to 150	°C

Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	I _D = 250μA, V _{GS} = 0V	40	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 40V, V _{GS} = 0V	-	-	1.0	μA
I _{GSS}	Gate-Body Leakage Current	V _{DS} = 0V, V _{GS} = ±20V	-	-	±100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250μA	1.2	1.8	2.4	V
R _{DS(ON)}	Static Drain-Source ON-Resistance ⁽³⁾	V _{GS} = 10V, I _D = 30A	-	2.5	3.3	mΩ
		V _{GS} = 4.5V, I _D = 15A	-	4.2	5.5	mΩ
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{GS} = 0V, V _{DS} = 20V, f = 1MHz	-	1815	-	pF
C _{oss}	Output Capacitance		-	523	-	pF
C _{rss}	Reverse Transfer Capacitance		-	39	-	pF
Q _g	Total Gate Charge	V _{GS} = 0 to 10V V _{DS} = 20V, I _D = 20A	-	24	-	nC
Q _{gs}	Gate Source Charge		-	3.5	-	nC
Q _{gd}	Gate Drain("Miller") Charge		-	4.5	-	nC
Switching Characteristics						
t _{d(on)}	Turn-On DelayTime	V _{GS} = 10V, V _{DD} = 20V I _D = 20A, R _{GEN} = 6Ω	-	5	-	ns
t _r	Turn-On Rise Time		-	9	-	ns
t _{d(off)}	Turn-Off DelayTime		-	23	-	ns
t _f	Turn-Off Fall Time		-	15.2	-	ns
Drain-Source Diode Characteristics and Max Ratings						
I _S	Maximum Continuous Drain to Source Diode Forward Current		-	-	96	A
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	384	A
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} = 0V, I _S = 30A	-	-	1.2	V
trr	Body Diode Reverse Recovery Time	I _F = 30A, di/dt = 100A/us	-	55	-	ns
Qrr	Body Diode Reverse Recovery Charge		-	47	-	nC

- Notes:
1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
 2. E_{AS} condition: Starting $T_J = 25^\circ\text{C}$, $V_{DD} = 20\text{V}$, $V_G = 10\text{V}$, $R_G = 25\Omega$, $L = 0.5\text{mH}$, $I_{AS} = 22\text{A}$
 3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 0.5\%$.

Test Circuit



Figure 1: Gate Charge Test Circuit & Waveform



Figure 2: Resistive Switching Test Circuit & Waveform

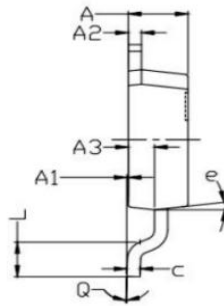
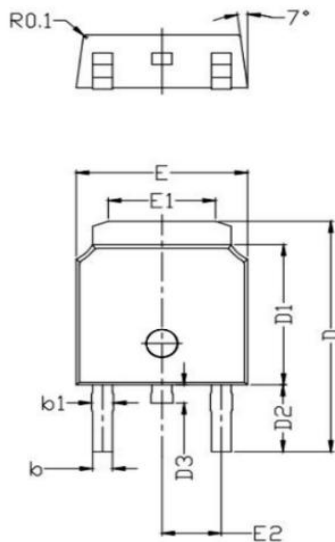


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform



Figure 4: Diode Recovery Test Circuit & Waveform

Package Mechanical Data(TO-252-3L)




COMMON DIMENSION (MM)			
PKG	TO-252-3L		
Symbol	MIN	NOM	MAX
A	2.250	2.300	2.400
A1	0.010	0.060	0.150
A2	0.500	0.508	0.550
A3	0.960	1.010	1.060
b	0.740	0.760	0.800
b1	0.880	0.900	0.950
c	0.500	0.508	0.550
D	9.800	10.025	10.350
D1	6.050	6.100	6.180
D2	2.850	2.900	2.950
D3	0.700	0.800	2.900
E	6.550	6.600	6.700
E1	4.050	4.130	4.200
E2	2.250	2.286	2.300
L	1.400	1.500	1.600
e	7		
Q	0°	2°	5°

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